



Discription

The HCESD923NC3V3B protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



SOD-923

Features

- ★ Ultra Low Capacitance 20 pF
- ★ Low Clamping Voltage
- ★ Small Body Outline Dimensions:
0.031" x 0.024" (0.80 mm x 0.60 mm)
- ★ Low Body Height: 0.015" (0.37 mm)
- ★ Stand-off Voltage: 3.3 V
- ★ Low Leakage
- ★ Response Time is Typically < 1.0 ns
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ This is a Pb-Free Device



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
HCESD923NC3V3B	SOD-923	8000

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20 μs)	110	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +155	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge contact discharge	±30 ±30 KV

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0*0.75*0.62 in.

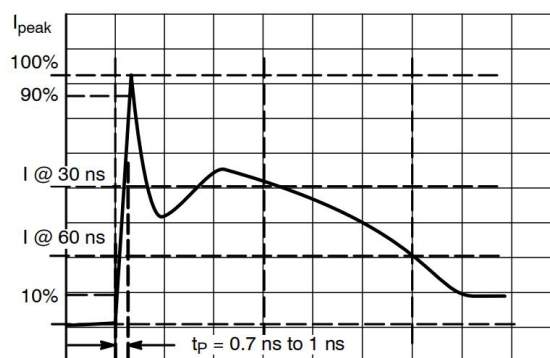
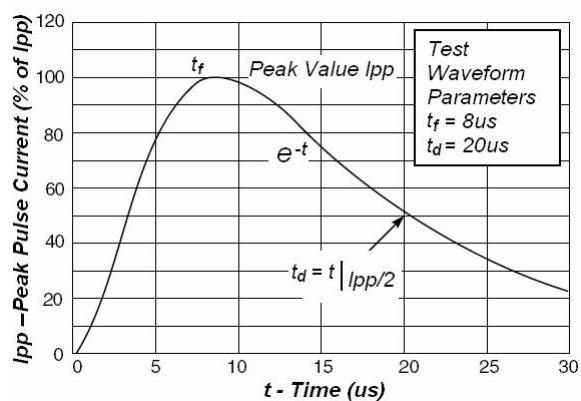


Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Device	V_{RWM} (V)	I_R (μA) @ V_{RWM}	V_{BR} (V) @ I_T (Note 2)	I_T	C (pF)	V_C (V) @ $I_{PP} = 1\text{ A}$	I_{PP} (A)	P_{pk} (W) (8*20 μs)
	Max	Max	Min	mA	Typ	Max	Max	Max
HCESD923NC3V3B	3.3	0.1	3.5	1.0	15	7.0	11	110

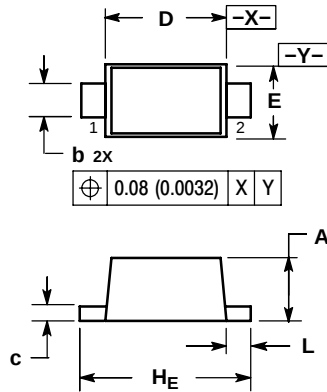
2. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C .

Typical Characteristics





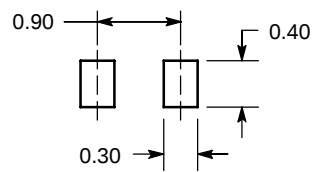
SOD-923 Outline And Dimensions



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
H _E	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS



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